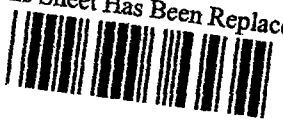
ABSTRACT

RESIN SEALING TYPE SEMICONDUCTOR DEVICE AND METHOD OF MAKING THE SAME

A resin sealing type semiconductor device includes a radiator, a semiconductor element, a frame lead arranged at a distance around this semiconductor element and displaced from the radiator, and a plurality of leads extending from this frame lead and attached to a mounting surface with a insulating lead support therebetween. The leads are pressed downward by an upper mold so that the radiator is pressed against a lower mold in such a manner that resin cannot seep therebetween. Thin portions are formed in the leads to ensure that the leads do not peel away from the insulating lead support.

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